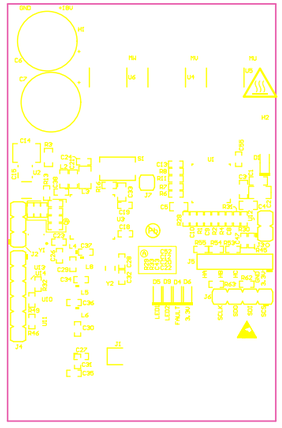
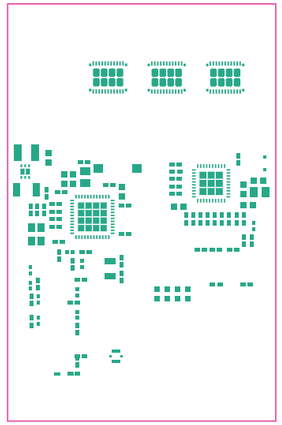
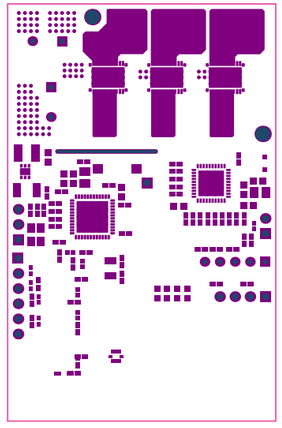


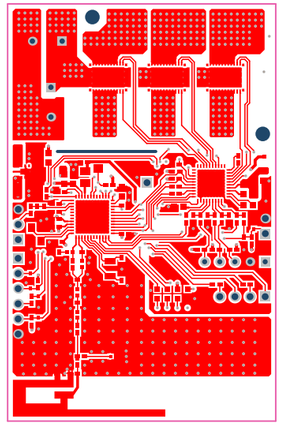
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01516	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01516		
Top Overlay	GENERATED : 2/9/2018 8:05:45 PM		TEXAS INSTRUMENTS



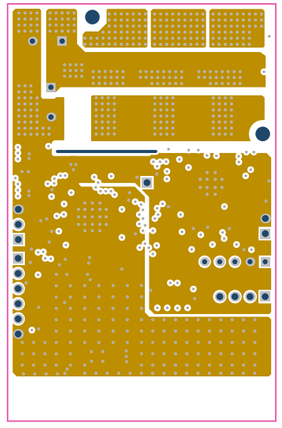
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01516	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Paste	TID #: TIDA-01516		
Top Paste	GENERATED : 2/9/2018 8:05:46 PM		TEXAS INSTRUMENTS



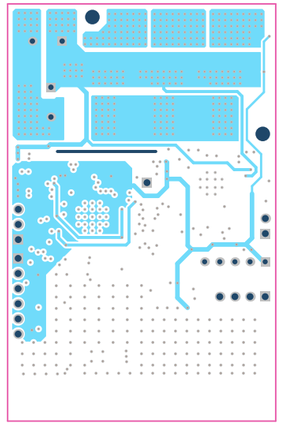
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01516	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01516		
Top Solder Mask	GENERATED : 2/9/2018 8:05:47 PM		TEXAS INSTRUMENTS



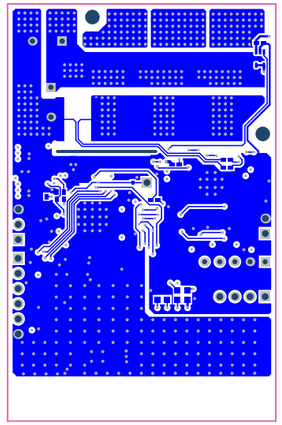
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01516	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01516		
Top Layer	GENERATED : 2/9/2018 8:05:48 PM		TEXAS INSTRUMENTS



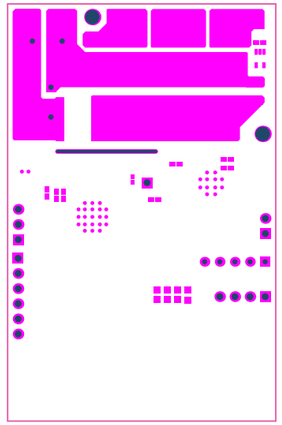
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01516	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = GND Layer	TID #: TIDA-01516		
GND	GENERATED : 2/9/2018 8:05:49 PM		TEXAS INSTRUMENTS



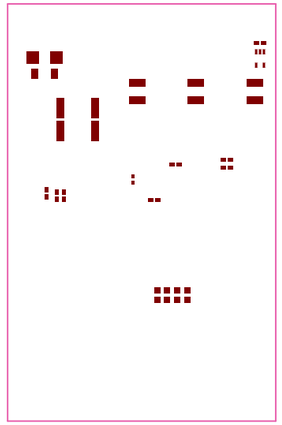
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01516	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = PWR Layer	TID #: TIDA-01516		
PWR	GENERATED : 2/9/2018 8:05:50 PM		TEXAS INSTRUMENTS



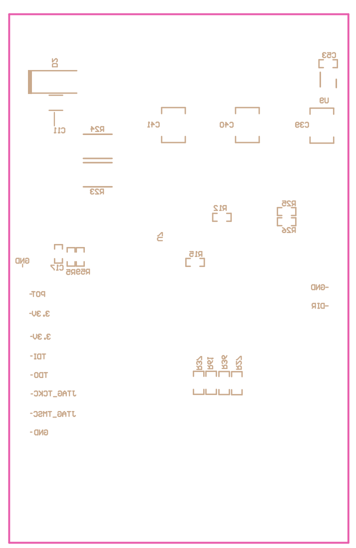
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01516	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01516		
Bottom Layer	GENERATED : 2/9/2018 8:05:51 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01516	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01516		
Bottom Solder Mask	GENERATED : 2/9/2018 8:05:51 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01516	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Paste	TID #: TIDA-01516		
Bottom Paste	GENERATED : 2/9/2018 8:05:52 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01516	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01516		
Bottom Overlay	GENERATED : 2/9/2018 8:05:53 PM		TEXAS INSTRUMENTS

IMPEDANCE TABLE:-

Layer	SE IMP (OHM) +/-10%	SE TRACE WIDTH IN MILS	REFERENCE Layer
Top Layer	50	7.874mil	GND Layer
GND Layer	-	-	-
PWR Layer	-	-	-
BOTTOM Layer	-	-	-

STACKUP_TABLE:-

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.38mil		
4	Dielectric1	FR-4 High Tg	6.88mil	4.8	
5	GND Layer	Copper	1.38mil		
6	Dielectric 2	FR-4 High Tg	43.70mil	4.2	
7	PWR Layer	Copper	1.38mil		
8	Dielectric 3	FR-4 High Tg	6.88mil	4.2	
9	Bottom Layer	Copper	1.38mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

Symbol	Count	Hole Size	Hole Length	Routed Path Length	Plated	Hole Type
□	1	20.00mil (0.508mm)	670.00mil (17.018mm)	650.00mil (16.510mm)	NPTH	Slot
◇	2	96.46mil (2.450mm)	-	-	NPTH	Round
◇	1	35.43mil (0.900mm)	-	-	PTH	Round
⊠	5	33.47mil (0.850mm)	-	-	PTH	Round
○	16	45.28mil (1.150mm)	-	-	PTH	Round
◎	270	10.00mil (0.254mm)	-	-	PTH	Round
✚	420	7.87mil (0.200mm)	-	-	PTH	Round
	718 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
45mm X 70mm

Number of Layers : 4
MIN. TRACK WIDTH: 7.874MIL
MIN. CLEARANCE: 7 MIL
MIN. VIA DRILL SIZE: 7.87 MIL
MINIMUM ANNULAR RING 5 MIL EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 63 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [X] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [X] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS: VIA TENTING: YES [X] NO [ ]
MICROSECTION: [ ] YES IMPEDANCE CONTROL: YES [X] NO [ ]
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

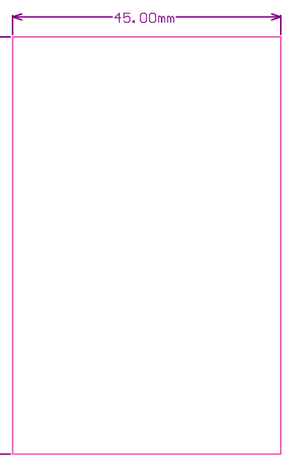
PROJECT TITLE:
18V, 600W BLDC Power Stage with BLE

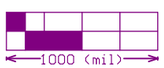
DESIGNED FOR:
Public Release

FILE NAME:
TIDA-01516_E2.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01516	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01516		
Drill Drawing	GENERATED : 2/9/2018 8:05:55 PM		TEXAS INSTRUMENTS

ENGINEER: Manu Balakrishnan
LAYOUT BY: Avinash N
SCALE: 1.00
ALTIUM DESIGNER VERSION: 17.1.5.472





ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01516	REV: E2	SVN REV: Not In VersionControl	
LAYER NAME =	TID #: TIDA-01516			
Board Dimensions	GENERATED : 2/9/2018 8:05:59 PM			TEXAS INSTRUMENTS

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